L Number	Hits	Search Text	DB	Time stamp
1	252073	battery	USPAT;	2004/09/02 07:55
2	1947	battery and 438/\$.ccls.	US-PGPUB USPAT; US-PGPUB	2004/09/02 07:55
3	341365	wiring interconnect	USPAT; US-PGPUB	2004/09/02 07:56
4	901	(battery and 438/\$.ccls.) and (wiring interconnect)	USPAT; US-PGPUB	2004/09/02 07:56
5	1584147	metal\$9	USPAT; US-PGPUB	2004/09/02 07:56
7	833	((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9	USPAT; US-PGPUB	2004/09/02 07:57
8	166856	wafer	USPAT; US-PGPUB	2004/09/02 07:57
9	427	(((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer	USPAT; US-PGPUB	2004/09/02 08:23
10	3701762	within between	USPAT; US-PGPUB	2004/09/02 08:31
18	1	("6650000").PN.	USPAT; US-PGPUB	2004/09/02 10:09
19	1070	battery with (wiring interconnect) with (within between)	USPAT; US-PGPUB	2004/09/02 10:18
20	853925	semiconductor integrated	USPAT; US-PGPUB	2004/09/02 10:18
21	388	(battery with (wiring interconnect) with (within between)) and (semiconductor integrated)	USPAT; US-PGPUB	2004/09/02 10:19
22	663496	substrate	USPAT; US-PGPUB	2004/09/02 10:19
23	708306	substrate wafer	USPAT; US-PGPUB	2004/09/02 10:19
25	128	((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)	USPAT; US-PGPUB	2004/09/02 10:21
26	78	(((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116	USPAT; US-PGPUB	2004/09/02 10:38
27	11	("2800616"   "3536963"   "3558357"   "3634736"   "3648126"   "3656027"   "4014730"   "4737422"   "5437941"   "5455126"   "6123861").PN.	USPAT	2004/09/02 10:35
28	5693	battery with (wiring interconnect)	USPAT; US-PGPUB	2004/09/02 10:38
29	538	(semiconductor integrated) and substrate and (battery with (wiring interconnect))	USPAT; US-PGPUB	2004/09/02 10:38
30	327	((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116	USPAT; US-PGPUB	2004/09/02 11:01
31	239	(((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not ((((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not ((((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116)	USPAT; US-PGPUB	2004/09/02 11:01
32	4012	battery with (substrate wafer)	USPAT; US-PGPUB	2004/09/02 11:01
33	805	(wiring interconnect) and (battery with (substrate wafer))	USPAT; US-PGPUB	2004/09/02 11:01
34	505	((wiring interconnect) and (battery with (substrate wafer))) and @ad<20010116	USPAT; US-PGPUB	2004/09/02 11:01
35	347	(((wiring interconnect) and (battery with (substrate wafer))) and @ad<20010116) not ((((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not ((((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not ((((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116)) not ((((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not ((((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not ((((battery with (wiring interconnect)) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116)	USPAT; US-PGPUB	2004/09/02 11:02

36	214	(semiconductor integrated) and ((((wiring interconnect) and (battery with	USPAT;	2004/09/02 11:02
		(substrate wafer))) and @ad<20010116) not ((((semiconductor integrated)	US-PGPUB	
		and substrate and (battery with (wiring interconnect))) and @ad<20010116)		
		not ((((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and	1	
		wafer) not ((((battery with (wiring interconnect) with (within between)) and		
	-	(semiconductor integrated)) and (substrate wafer)) and @ad<20010116)) not		
		(((semiconductor integrated) and substrate and (battery with (wiring		
		interconnect))) and @ad<20010116) not ((((battery and 438/\$.ccls.) and		
		(wiring interconnect)) and metal\$9) and wafer) not ((((battery with (wiring		
		interconnect) with (within between)) and (semiconductor integrated)) and		
1	1	(substrate wafer)) and @ad<20010116))		